Form PTO-1595 1-31/92



## 12-14-1998



U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: I	Please record the attached original documents or copy thereof	
Name of Conveying Part(ies):  Dendhis D.C. Thelese	2. Name and address of receiving party(ies):	
Randhir P.S. Thakur	Name: <u>Micron Technology, Inc.</u>	
	Internal Address:	
Additional name(s) of conveying party(ies) attached?		
MRD 12.7.98		
3. Nature of conveyance:	Street Address: 8000 South Federal Way	
Assignment   Security Agreement  Merger   Change of Name		
☐ Other	City: <u>Boise</u> State: <u>ID</u> Zip: <u>83706</u>	
Execution Date:10/14/1998		
	Additional names(s) & address(es) attached:   Yes  No	
<ol> <li>Application number(s) or patent number(s):         If this document is being filed together with a ris:      </li> </ol>	new application, the execution date of the application	
A.Patent Application No.(s): 09/138,773	B.Patent No.(s)	
Additional numbers attached:   Yes  No	Additional numbers attached:   Yes  No	
<ol> <li>Name and address of party to whom correspondence concerning document should be mailed:</li> <li>Name: Mark S. Matkin</li> </ol>	6. Total number of applications and patents involved	
Internal Address: Wells, St. John, Roberts,	7. Total fee (37 CFR 3.41)	
Gregory & Matkin P.S.		
Street Address: 601 W. First Avenue, Ste. 1300	8. Deposit account number	
City: Spokane State: WA Zip: 99201-3828	(Attach duplicate copy of this page if paying by deposit account)	
DO NOT USE	THIS SPACE	
9. Statement and Signature.  To the best of my knowledge and belief, the foregoing information is true and correl and any attached copy is a true copy of the original document.		
Mark S. Matkin	12/1/98	
Name of Person Signing	Signature Date	
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OMB No. 0651-0011 (exp. 9/94)		
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Assistant Commissioner for Patents Box Assignments Washington, D.C. 20231		
Public burden reporting for this sample cover sheet is estimated to average about 30 minutes per document to be recorded, including time for reviewing the document and gathering the data needed, and completing and reviewing the sample cover sheet. Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Office of Information Systems, PK2-1000C, Washington, D.C. 20231, and to the Office of Management and Budget, Paperwork Reduction Project (0651-0011), Washington, D.C. 20503.		

PATENT REEL: 9628 FRAME: 0912

## PATENT ASSIGNMENT

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**ASSIGNEE:** 

Randhir P.S. Thakur

INVENTOR:

Micron Technology, Inc. Corporation of the State of Delaware 8000 South Federal Way Boise, Idaho 83706-9632

PARTIES TO THE ASSIGNMENT:

## **BACKGROUND OF THIS ASSIGNMENT:**

INVENTOR has conceived certain new and useful inventions disclosed in a United States patent application titled Methods To Form Electronic Devices And Methods To Form A Material Over A Semiconductive Substrate, Serial No. 09/138,773, filed August 24, 1998.

MICRON TECHNOLOGY, INC. desires to acquire the entire right, title and interest in said inventions and with respect to any Letters Patent that may be granted with respect to the inventions in both the United States and in all foreign countries.

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## THE PARTIES AGREE AS FOLLOWS:

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In consideration of good and valuable consideration, the receipt sufficiency and adequacy of which is hereby acknowledged, INVENTOR hereby sells, assigns and transfers to MICRON TECHNOLOGY, INC. the entire right and interest in the above-identified application and to any reissues, renewals, divisions or continuations thereof, and hereby authorizes the Commissioner of Patents and Trademarks to issue such Letters Patent to MICRON TECHNOLOGY, INC. for the sole use of MICRON TECHNOLOGY, INC., its successors or assigns.

INVENTOR further agrees to execute, at the request and expense of MICRON TECHNOLOGY, INC. such other formal documents as may be required to fully convey the interest transferred herein and will similarly execute any application papers required for the filing of any division, continuation, renewal or reissue of the patent application or resulting Letters Patent; and will generally do everything necessary or desirable to obtain and enforce proper protection for the invention assigned hereby.

INVENTOR further assigns to MICRON TECHNOLOGY, INC. the whole right, title and interest in the inventions disclosed in the application throughout all countries foreign to the United States. TECHNOLOGY, INC. is hereby authorized to apply for patents relating to the inventions in its own name in countries where such procedure is proper; to claim the benefit of the International Convention; to file and prosecute International Applications relating to

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the inventions under the Patent Cooperation Treaty; and to file and prosecute applications relating to the inventions under the European Patent Convention. INVENTOR agrees to execute applications relating to the inventions in those countries and under those conventions where it is necessary that the same be executed by the inventor, and to execute assignments of such applications and the resulting Letters Patent to MICRON TECHNOLOGY, INC. as well as all other necessary papers in relation to such applications and Letters Patent.

INVENTOR further warrants and covenants that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full rights to convey the same as herein expressed is possessed by the undersigned.

To be binding on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignees.

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,	(Signature) Randhin PS Thakmy Date:	10/14/48
•	Randhir P.S. Thakur	
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4	County of Santa Clara ) ss.	
5	BEFORE ME, this 14th day of OCTOBER personally appeared the above-named inventor, to me kno	19 <b>9</b>
6		ng assignment
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8	SEAL SEAL	
9		· Ca
10	Notary or Consular Officer  My Commission Expires: No.	. 27, 1998
11	n	
12	WALTER L. SMITH JR. COMM. #1045319	
13	NOTARY PUBLIC-CALIFORNIA SANTA CLARA COUNTY My Comm. Expires Nov. 27,1998	
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**RECORDED: 12/07/1998**